74VHC541; 74VHCT541

Octal buffer/line driver; 3-state

Rev. 01 — 12 August 2009 Product data sheet

1. General description

The 74VHC541; 74VHCT541 are high-speed Si-gate CMOS devices.

The 74VHC541; 74VHCT541 are octal non-inverting buffer/line drivers with 3-state bus compatible outputs.

The 3-state outputs are controlled by the output enable inputs $\overline{OE}0$ and $\overline{OE}1$.

A HIGH on $\overline{OE}n$ causes the outputs to assume a high-impedance OFF-state.

2. Features

- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accepts voltages higher than V_{CC}
- The 74VHC541 operates with CMOS input level
- The 74VHCT541 operates with TTL input level
- ESD protection:
  - HBM JESD22-A114E exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from –40 °C to +85 °C and from –40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74VHC541D	–40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74VHCT541D				
74VHC541PW	–40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74VHCT541PW				
74VHC541BQ	–40 °C to +125 °C	DHVQFN20	plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
74VHCT541BQ				

NXP founded by Philips

4. Functional diagram

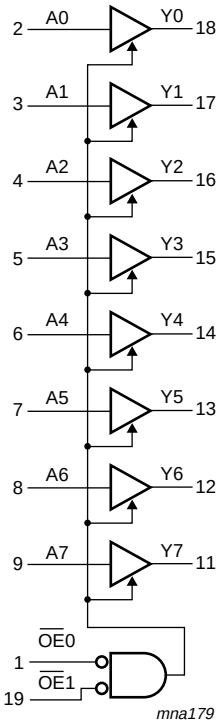

Fig 1. Logic symbol

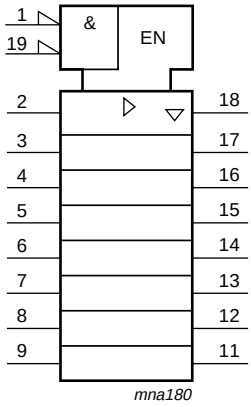

Fig 2. IEC logic symbol

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5. Pinning information

5.1 Pinning

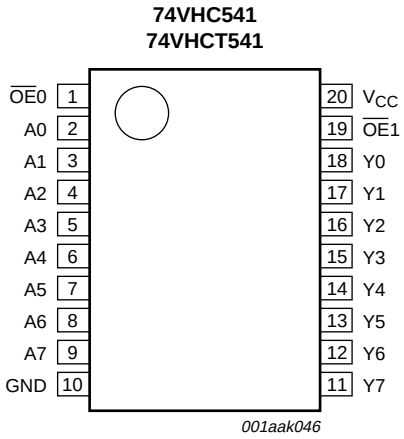
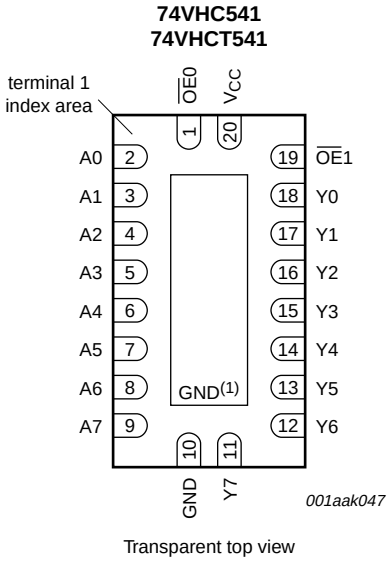


Fig 3. Pin configuration SO20, TSSOP20



Transparent top view

(1) The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig 4. Pin configuration DHVQFN20

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}0$	1	output enable input (active LOW)
A[0:7]	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y[0:7]	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}1$	19	output enable input (active LOW)
V_{CC}	20	supply voltage

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6. Functional description

Table 3. Functional table[1]

Control		Input	Output
$\overline{OE0}$	$\overline{OE1}$	An	Yn
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level;
L = LOW voltage level;
X = don't care;
Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+7.0	V
V_I	input voltage			–0.5	+7.0	V
I_{IK}	input clamping current	$V_I < -0.5$ V	[1]	–20	-	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1]	-	±20	mA
I_O	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)		-	±25	mA
I_{CC}	supply current			-	75	mA
I_{GND}	ground current			–75	-	mA
T_{stg}	storage temperature			–65	+150	°C
P_{tot}	total power dissipation	T_{amb} = –40 °C to +125 °C				
	SO20 package		[2]	-	500	mW
	TSSOP20 package		[3]	-	500	mW
	DHVQFN20 package		[4]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

[4] P_{tot} derates linearly with 4.5 mW/K above 60 °C.

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8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74VHC541			74VHCT541			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V_I	input voltage		0	-	5.5	0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		–40	+25	+125	–40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 3.3 V ± 0.3 V	-	-	100	-	-	-	ns/V
		V_{CC} = 5.0 V ± 0.5 V	-	-	20	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
For type 74VHC541										
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	V
		V_{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	V
		V_{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	-	0.5	-	0.5	V
		V_{CC} = 3.0 V	-	-	0.9	-	0.9	-	0.9	V
		V_{CC} = 5.5 V	-	-	1.65	-	1.65	-	1.65	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = –50 µA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I_O = –50 µA; V_{CC} = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I_O = –50 µA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –4.0 mA; V_{CC} = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I_O = –8.0 mA; V_{CC} = 4.5 V	3.94	-	-	3.8	-	3.70	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = 50 µA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 50 µA; V_{CC} = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 50 µA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 4.0 mA; V_{CC} = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I_O = 8.0 mA; V_{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I_{OZ}	OFF-state output current	V_I = V_{IH} or V_{IL}; V_O = V_{CC} or GND; V_{CC} = 5.5 V	-	-	±0.25	-	±2.5	-	±10.0	µA
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	4.0	-	40	-	80	µA

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Table 6. Static characteristics *…continued*

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C_I	input capacitance		-	3.0	10	-	10	-	10	pF
C_O	output capacitance		-	4.0	-	-	-	-	-	pF
For type 74VHCT541										
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = –50 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –8.0 mA	3.94	-	-	3.8	-	3.70	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}; V_{CC} = 4.5 V								
		I_O = 50 μA	-	0	0.1	-	0.1	-	0.1	V
		I_O = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I_{OZ}	OFF-state output current	per input pin; V_I = V_{IH} or V_{IL}; V_{CC} = 5.5 V; I_O = 0 A; V_O = V_{CC} or GND; other pins at V_{CC} or GND	-	-	±0.25	-	±2.5	-	±10.0	μA
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	4.0	-	40	-	80	μA
ΔI_{CC}	additional supply current	per input pin; V_I = V_{CC} – 2.1 V; I_O = 0 A; other pins at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C_I	input capacitance		-	3	10	-	10	-	10	pF
C_O	output capacitance		-	4.0	-	-	-	-	-	pF

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10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V. For test circuit see Figure 7.

Symbol	Parameter	Conditions		25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	
For type 74VHC541											
t_{pd}	propagation delay	An to Yn; see Figure 5	[2]								
		V_{CC} = 3.0 V to 3.6 V									
		C_L = 15 pF		-	5.0	7.0	1.0	8.5	1.0	9.0	ns
		C_L = 50 pF		-	7.0	10.5	1.0	12.0	1.0	13.5	ns
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	3.5	5.0	1.0	6.0	1.0	6.5	ns
		C_L = 50 pF			5.0	7.0	1.0	8.0	1.0	9.0	ns
t_{en}	enable time	$\overline{OE}$n to Yn; see Figure 6	[2]								
		V_{CC} = 3.0 V to 3.6 V									
		C_L = 15 pF		-	5.5	10.5	1.0	11.0	1.0	13.5	ns
		C_L = 50 pF		-	7.5	14.0	1.0	16.0	1.0	17.5	ns
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	3.5	7.2	1.0	8.5	1.0	9.0	ns
		C_L = 50 pF		-	5.0	9.2	1.0	10.5	1.0	11.5	ns
t_{dis}	disable time	$\overline{OE}$n to Yn; see Figure 6	[2]								
		V_{CC} = 3.0 V to 3.6 V									
		C_L = 15 pF		-	6.0	11.0	1.0	12.0	1.0	14.0	ns
		C_L = 50 pF		-	9.5	15.4	1.0	17.5	1.0	19.5	ns
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	4.5	7.5	1.0	8.0	1.0	9.5	ns
		C_L = 50 pF		-	6.5	8.8	1.0	10.0	1.0	11.0	ns
C_{PD}	power dissipation capacitance	C_L = 50 pF; f_i = 1 MHz; V_I = GND to V_{CC}	[3]	-	10	-	-	-	-	-	pF

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Table 7. Dynamic characteristics *…continued*

GND = 0 V. For test circuit see Figure 7.

Symbol	Parameter	Conditions		25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	
For type 74VHCT541											
t_{pd}	propagation delay	An to Yn; see Figure 5	[2]								
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	3.5	5.5	1.0	6.5	1.0	7.0	ns
		C_L = 50 pF		-	5.0	8.5	1.0	9.5	1.0	11.0	ns
t_{en}	enable time	$\overline{OE}$n to Yn; see Figure 6									
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	4.0	7.0	1.0	8.0	1.0	9.0	ns
		C_L = 50 pF		-	5.5	10.0	1.0	12.0	1.0	12.5	ns
t_{dis}	disable time	$\overline{OE}$n to Yn; see Figure 6	[2]								
		V_{CC} = 4.5 V to 5.5 V									
		C_L = 15 pF		-	5.0	7.0	1.0	8.0	1.0	9.0	ns
		C_L = 50 pF		-	7.0	10.0	1.0	12.0	1.0	12.5	ns
C_{PD}	power dissipation capacitance	per buffer; C_L = 50 pF; f = 1 MHz; V_I = GND to V_{CC}	[3]	-	12	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] C_{PD} is used to determine the dynamic power dissipation P_D (µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in Volts.

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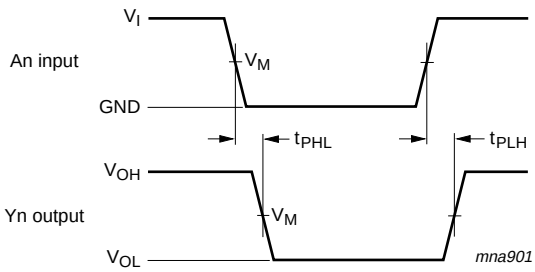
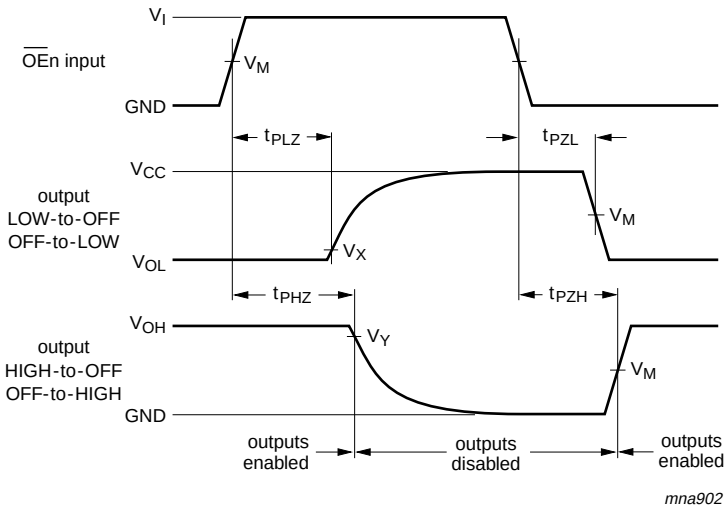
11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Propagation delay input (An) to output (Yn)



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
74VHC541	$0.5V_{CC}$	$0.5V_{CC}$	V_{OL} + 0.3 V	V_{OH} – 0.3 V
74VHCT541	1.5 V	$0.5V_{CC}$	V_{OL} + 0.3 V	V_{OH} – 0.3 V

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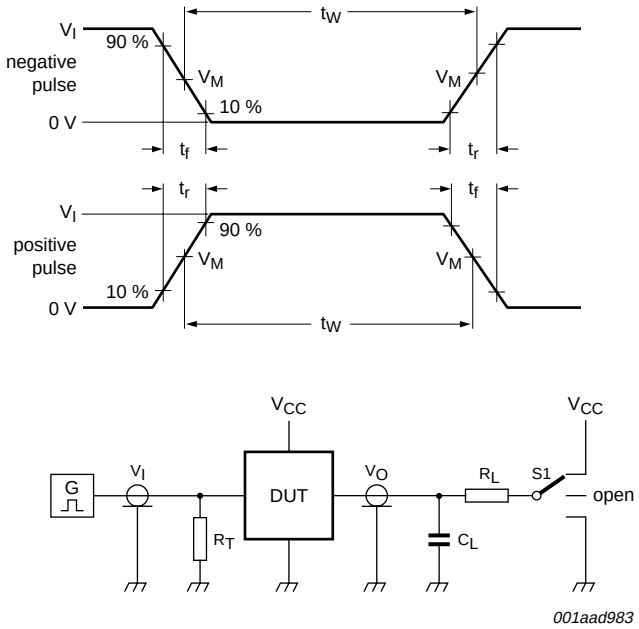

Test data is given in Table 9.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

R_L = Load resistor

S1 = Test selection switch

Fig 7. Load circuitry for switching times

Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74VHC541	V_{CC}	3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}
74VHCT541	3.0 V	3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}

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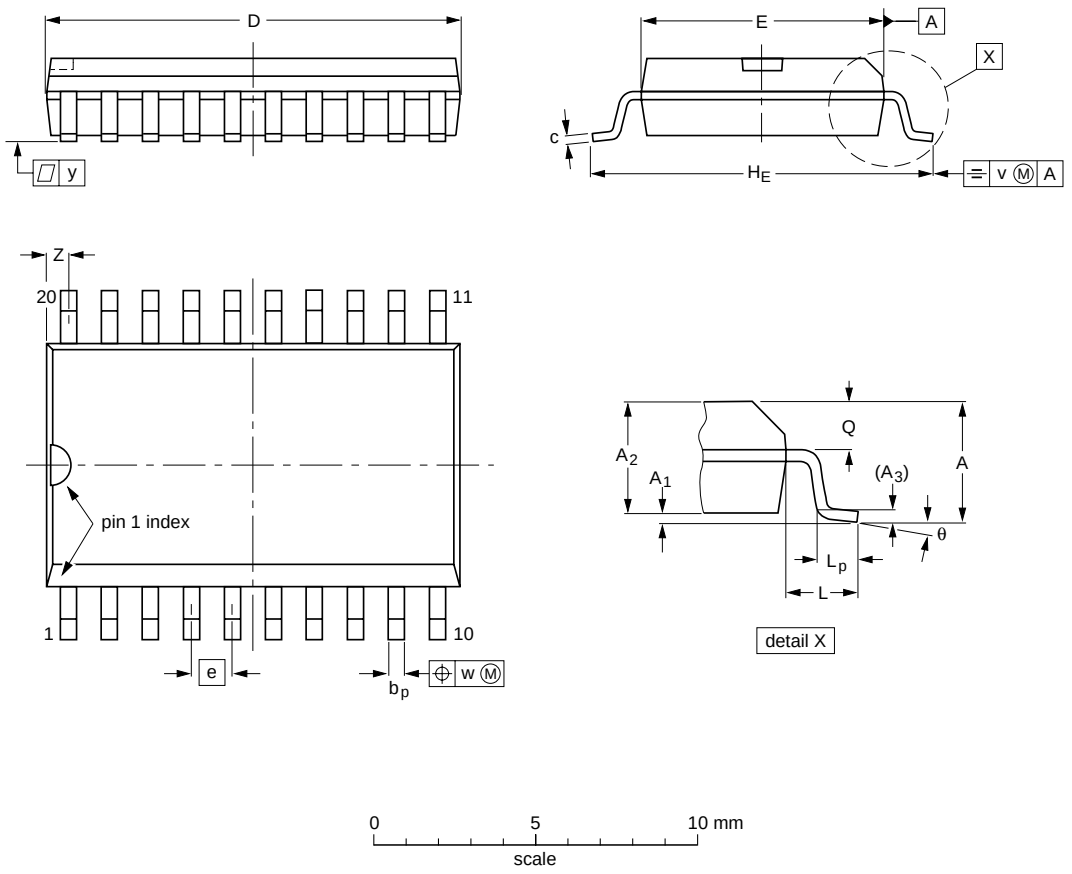
12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 8. Package outline SOT163-1 (SO20)

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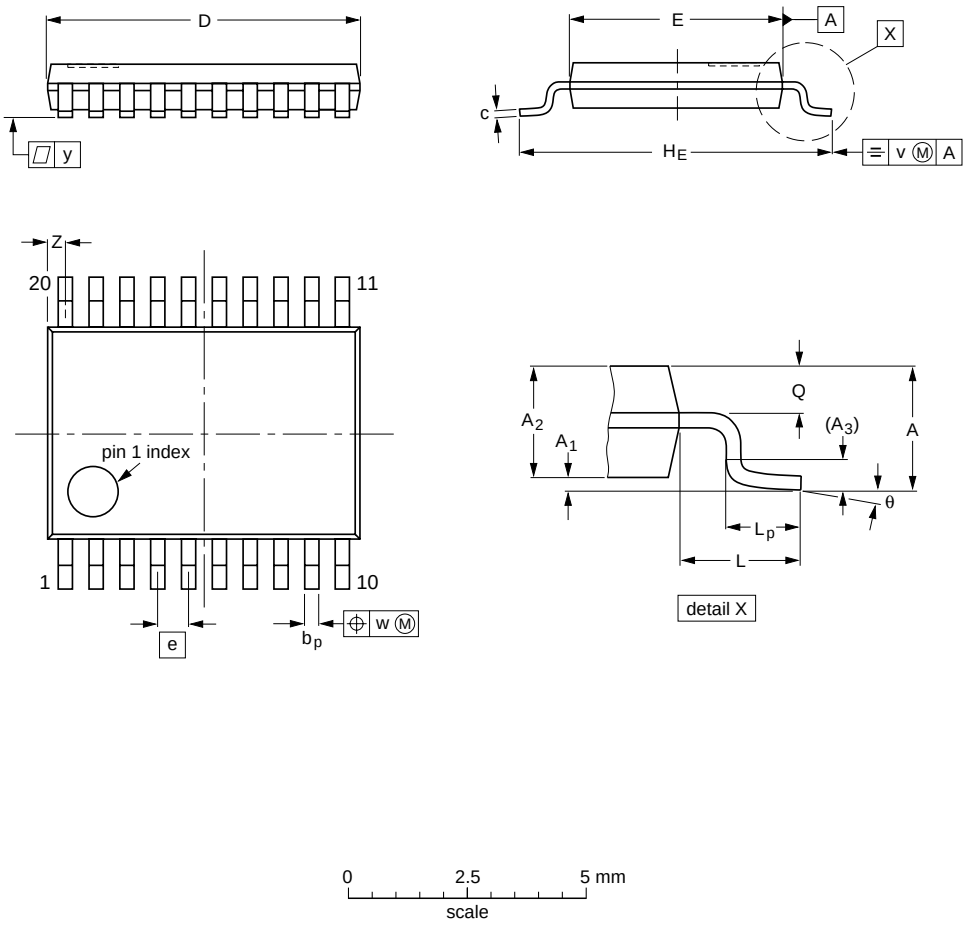
TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT360-1 (TSSOP20)

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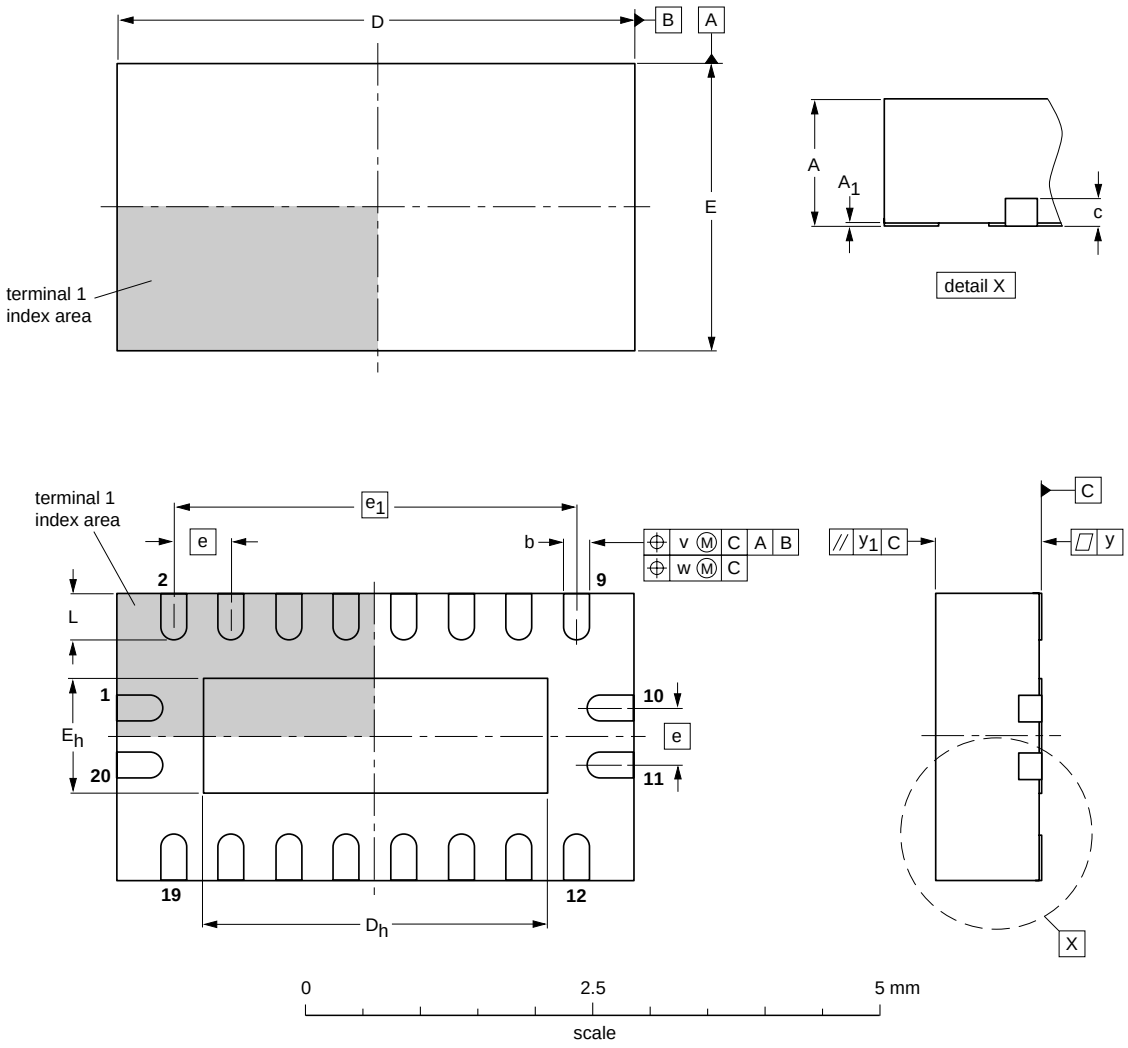
DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm **SOT764-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	4.6 4.4	3.15 2.85	2.6 2.4	1.15 0.85	0.5	3.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT764-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

Fig 10. Package outline SOT764-1 (DHVQFN20)

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13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74VHC_VHCT541_1	20090812	Product data sheet	-	-

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15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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17. Contents

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Date of release: 12 August 2009

Document identifier: 74VHC_VHCT541_1

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PHILIPS

74VHC_VHCT541 Preview Product information Selection guide

Datasheet

(Product Specification)
v.1.1, 2010-02-17
Pages, 96kB

Download datasheet
Download all documentation

Octal buffer_line driver; 3-state

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General description

Hide

The 74VHC541; 74VHCT541 are high-speed Si-gate CMOS devices.

The 74VHC541; 74VHCT541 are octal non-inverting buffer/line drivers with 3-state bus compatible outputs.

The 3-state outputs are controlled by the output enable inputs OE0 and OE1.

A HIGH on OEn causes the outputs to assume a high-impedance OFF-state.

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Features and benefits

Hide

- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accepts voltages higher than VCC
- The 74VHC541 operates with CMOS input level
- The 74VHCT541 operates with TTL input level
- ESD protection:
  - HBM JESD22-A114E exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

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Pricing/ordering/availability

Hide

Type number	Ordering code(12NC)	Orderable part number	Region	Distributor	In stock	Order quantity	Inventory date	Buy online	Samples
74VHC541BQ	9352 895 17115	74VHC541BQ,115	NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	Order samples
			NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	
74VHC541D	9352 895 22118	74VHC541D,118	NA	MOUSER ELECTRONICS	475		5/14/2011	Buy online	Order samples
			NA	MOUSER ELECTRONICS	475		5/14/2011	Buy online	
74VHC541PW	9352 895 27118	74VHC541PW,118	NA	DIGI-KEY CORPORATION	4,917		5/14/2011	Buy online	Order samples
			NA	DIGI-KEY CORPORATION	2,500		5/14/2011	Buy online	
			NA	MOUSER ELECTRONICS	465		5/14/2011	Buy online	
			NA	MOUSER ELECTRONICS	465		5/14/2011	Buy online	
74VHCT541BQ	9352 895 18115	74VHCT541BQ,115	NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	Order samples
			NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	
74VHCT541D	9352 895 23118	74VHCT541D,118	NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	Order samples
			NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	
74VHCT541PW	9352 895 28118	74VHCT541PW,118	NA	DIGI-KEY CORPORATION	4,840		5/14/2011	Buy online	Order samples
			NA	DIGI-KEY CORPORATION	2,500		5/14/2011	Buy online	
			NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	
			NA	MOUSER ELECTRONICS	500		5/14/2011	Buy online	

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Products/packages

Hide

Type number	Orderable part number	Ordering code (12NC)	Product status	Package	Packing	Marking	ECCN
74VHC541BQ	74VHC541BQ,115	9352 895 17115	Volume production	SOT764-1 (DHVQFN20)	Reel Pack, SMD, 7"	Standard Marking	
74VHC541D	74VHC541D,118	9352 895 22118	Volume production	SOT163-1 (SO20)	Tape reel smd	Standard Marking	
74VHC541PW	74VHC541PW,118	9352 895 27118	Volume production	SOT360-1 (TSSOP20)	Reel Pack, SMD, 13"	Standard Marking	
74VHCT541BQ	74VHCT541BQ,115	9352 895 18115	Volume production	SOT764-1 (DHVQFN20)	Reel Pack, SMD, 7"	Standard Marking	
74VHCT541D	74VHCT541D,118	9352 895 23118	Volume production	SOT163-1 (SO20)	Tape reel smd	Standard Marking	
74VHCT541PW	74VHCT541PW,118	9352 895 28118	Volume production	SOT360-1 (TSSOP20)	Reel Pack, SMD, 13"	Standard Marking	

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Quality/reliability/chemical content Hide

Type number	Orderable part number	Chemical content	RoHS	Leadfree conversion date	RHF	IFR (FIT)	MTBF (hours)	MSL	MSL LF
74VHC541BQ	74VHC541BQ,115	74VHC541BQ	EU/CN RoHs COMPLIANT	Always Pb-free	D			1	1
74VHC541D	74VHC541D,118	74VHC541D	EU/CN RoHs COMPLIANT	Always Pb-free	G			1	1
74VHC541PW	74VHC541PW,118	74VHC541PW	EU/CN RoHs COMPLIANT	Always Pb-free	D			1	1
74VHCT541BQ	74VHCT541BQ,115	74VHCT541BQ	EU/CN RoHs COMPLIANT	Always Pb-free	D			1	1
74VHCT541D	74VHCT541D,118	74VHCT541D	EU/CN RoHs COMPLIANT	Always Pb-free	G			1	1
74VHCT541PW	74VHCT541PW,118	74VHCT541PW	EU/CN RoHs COMPLIANT	Always Pb-free	D			1	1

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